



SOT549-3

plastic thermal enhanced thin shrink small outline package;
32 leads; body width 6.1 mm; lead pitch 0.65 mm; exposed
die pad

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	HTSSOP32
Package type industry code	HTSSOP32
Package style descriptive code	HTSSOP (thermal enhanced thin shrink small outline package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MO-153
Mounting method type	S (surface mount)
Issue date	2-11-2005

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		10.9	-	11	11.1	mm
E	package width		6	-	6.1	6.2	mm
A	seated height		[tbd]	-	1.1	1.1	mm
A ₂	package height		0.85	-	0.9	0.95	mm
n ₂	actual quantity of termination		-	-	32	-	



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2. Package outline

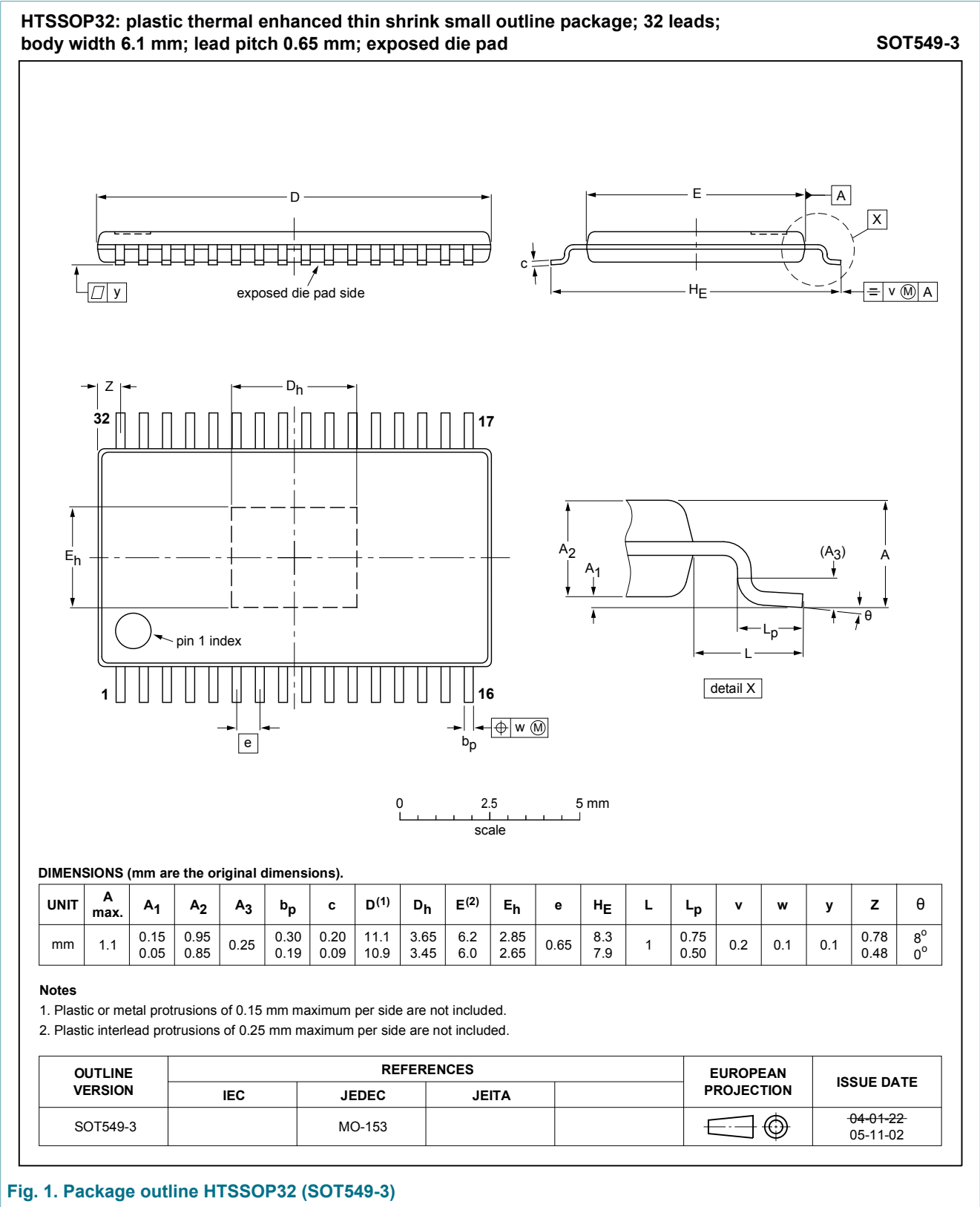


Fig. 1. Package outline HTSSOP32 (SOT549-3)

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3. Soldering

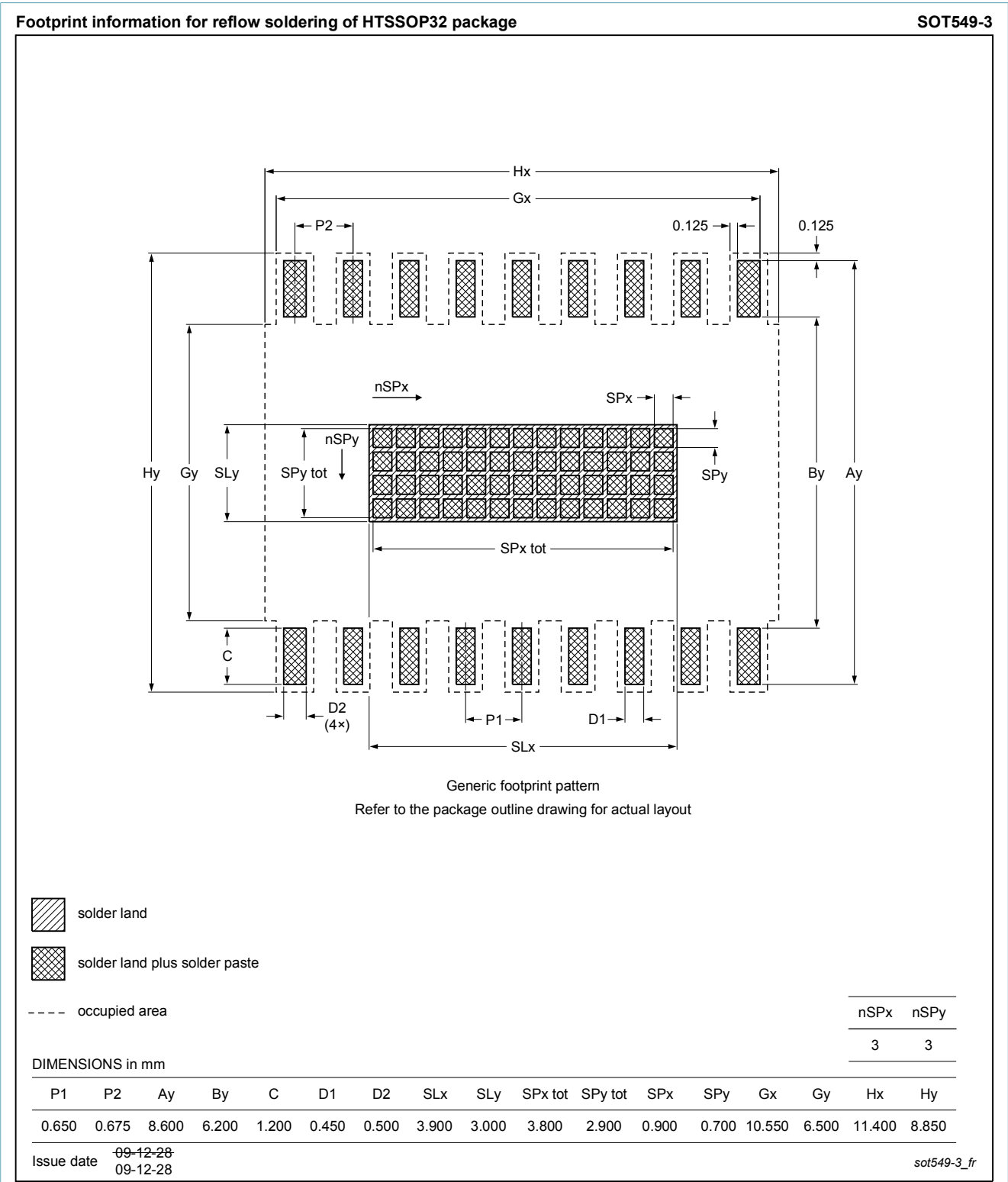


Fig. 2. Reflow soldering footprint for HTSSOP32 (SOT549-3)

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4. Legal information

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